

PATENT  
EXPEDITED PROCEDURE  
UNDER 37 CFR 1.116  
GROUP 2853

B1 Sub C1  
a substrate associated with said backside of said heater chip, said substrate having a substantially flat surface opposing said at least one cavity; and

5 adhesive at least partially disposed within said at least one cavity, said adhesive adhering said backside of said heater chip to said substantially flat surface of said substrate.

B2 Sub C1  
5. (Amended) The printhead assembly of claim 2, wherein said heater chip includes a plurality of ink vias, said adhesive being configured for preventing fluid communication between said plurality of ink vias in an area defined between said heater chip and said substrate.

B3 Sub C1  
8. (Amended) An ink jet printhead assembly, comprising:  
a heater chip including a backside with at least one cavity;  
a substrate associated with said backside of said heater chip, said substrate having a substantially flat surface; and  
5 adhesive substantially entirely disposed within said at least one cavity, said adhesive adhering said backside of said heater chip to said substantially flat surface of said substrate.

REMARKS

Based on the corrected Office Action of December 11, 2001, claims 1-15, 17 and 19-21 are pending, claims 1-7, 9-15, 17 and 19-21 are rejected, and claim 8 is objected to in this